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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/527,056	10/20/2005	Woo-Seok Cheong	123034-05029639	6957

22429 7590 09/15/2008  
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EXAMINER
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FORD, NATHAN K

ART UNIT	PAPER NUMBER
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1792

MAIL DATE	DELIVERY MODE
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09/15/2008

PAPER

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

<b>Office Action Summary</b>	<b>Application No.</b> 10/527,056	<b>Applicant(s)</b> CHEONG ET AL.	
	<b>Examiner</b> NATHAN K. FORD	<b>Art Unit</b> 1792	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 5/27/08.
- 2a) ☐ This action is **FINAL**.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 6-14 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 6-14 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 09 March 2005 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All    b) ☐ Some \*    c) ☐ None of:
1. ☒ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)            | 4) <input type="checkbox"/> Interview Summary (PTO-413)           |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)   | Paper No(s)/Mail Date. _____                                      |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date <u>10/20/05, 6/12/07</u> .                                       | 6) <input type="checkbox"/> Other: _____                          |

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**DETAILED ACTION***Election*

Claims 1-5 are withdrawn from further consideration pursuant to 37 CFR 1.142(b), as being drawn to a nonelected apparatus, there being no allowable generic or linking claim. The applicant has timely traversed the restriction (election) requirement in the reply filed on 5/27/08.

The applicant's traversal has been fully considered but is not persuasive. The inventions have acquired a separate status in the art in view of their different classifications and divergent subject matter. Further, an apparatus and method necessitate different fields of search. For these reasons, the restriction is maintained.

*Claim Rejections - 35 USC § 103*

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 6-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine et al., US 6,488,778, in view of Shao et al., US 6,437,290.

Regarding those features of claim 1 incorporated in the present claim, Ballantine teaches the following (Fig. 1):

- A first chamber (20) comprising:
  - A first substrate holder (24) positioned in a lower portion of the chamber;
  - A lamp provided in the upper portion of the chamber (4, 38-42);
  - A substrate door (4, 38-39);
- A second chamber, taken to include both units 40 and 50, comprising:
  - A second substrate holder (44) provided in the lower portion of the second chamber and capable of changing temperature when exposed to heat;
  - A middle film, taken to be the "selectively opened" demarcation between chambers 40 and 50, provided in the middle portion of the chamber (5, 1-6);
  - An elevating portion (46) attached to the second substrate holder;

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- Wherein an LPCVD chamber must inherently comprise a metal depositing portion;
- A pumping portion (4, 47-50);
- Gas injecting portions (4, 32-45);
- Each chamber is selectively open to adjacent chamber -- this is the denotation of a gate valve.

Although Ballantine incorporates arrays of heating lamps, he does not specify whether these lamps are of the halogen type. Nevertheless, halogen lamps are well-known in the art. For example, Shao avails halogen lamps (51) to irradiate a sample, thereby demonstrating the suitability of using lamps of the halogen type for such purposes (10, 36-49). It would have been obvious to one of ordinary skill in the art at the time the invention was made to incorporate halogen lamps within the first chamber of Ballantine's apparatus to achieve the predictable result of irradiating a sample.

Claim 6: Ballantine teaches the following:

- Cleaning a substrate via "hot processing" using the first chamber (20) (4, 30ff);
- Moving the substrate into the second chamber (40, 50);
- Depositing a metal film in the second chamber (claims 11, 19-21);
- Wherein the steps are performed in a batch process without exposure to ambient air (claim 11).

Claim 7: The substrate is heated following the onset of deposition (6, 17-48).

Claim 8 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine and Shao in view of Tsao, US 4,752,815.

Ballantine is silent regarding the growth of an oxide film. Tsao applies an oxide layer which is removed and then regrown to reduce the mechanical stress of the structure (3, 37-40). For this reason, it would have been obvious to one of ordinary skill in the art at the time the invention was made to form an oxide layer in the second chamber of Ballantine prior to metal deposition, wherein the apparatus is capable of forming an oxide layer.

Claims 9 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine and Shao in view of Tsao and in further view of Beinglass et al., US 5,940,733.

The rejection under claim 6 limits the features of claim 1 that are taught by Ballantine and incorporate herein.

Claim 9: Tsao teaches the following:

- Positioning a substrate in a first chamber;

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- The sequence of forming the following on said substrate (3, 20 - 4, 25):
  - A silicon layer (12);
  - A gate oxide layer (20);
  - A gate electrode (30);
  - A spacer (44, 46).

Tsao merely discloses the method of fabricating a schottky barrier MOSFET and is silent regarding the deposition structures which facilitate the fabrication process. Ballantine and Shao as applied to claim 1, however, disclose a deposition apparatus suitable for the fabrication of a schottky barrier MOSFET. As cited above, Ballantine teaches a method of cleaning a substrate using a first chamber prior to its transfer to a second chamber via a connecting portion to undergo deposition. A metal film is deposited by an LPCVD chamber, wherein the substrate is inserted vertically into the chamber. Thus, Ballantine and Shao provide the structural elements to facilitate the method disclosed by Tsao. It would have been obvious to one of ordinary skill in the art at the time the invention was made to perform the method of MOSFET fabrication disclosed by Tsao within the apparatus of Ballantine to achieve the predictable result of manufacturing a schottky barrier MOSFET.

Tsao does not address the further step of growing a silicide following the deposition of the metal film. Beinglass, disclosing a method of fabricating a polysilicon silicide composite, supplements this omission. Following the deposition of a metal layer, Beinglass transfers the substrate into another chamber for the express purpose of developing a silicide layer via heating at 500-600 degrees Celsius, as is well-known in the art (Abstract; 1, 17-39). Thus, considering Beinglass's general teaching of forming a silicide in a chamber distinct from that which the metal layer was deposited, it would have been obvious to one of ordinary skill in the art at the time the invention was made to form a silicide layer in a first chamber, as the metal deposition occurs in Ballantine's LPCVD chamber, that is, the second chamber. During the process of substrate transfer, the substrate is both "pulled up" and "pulled down."

Claim 10: Tsao applies an oxide layer which is removed and then regrown to reduce the mechanical stress of the structure (3, 37-40).

Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine and Shao in view of Tsao and Beinglass, and in further view of Brabant et al., US 2003/0036268 and Chang et al., 5,043,299.

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Ballantine is silent regarding the condition of cleaning. Supplementing the omission is Chang, who discloses a method of selective tungsten deposition. Chang executes a hydrogen cleaning step (3, 20-25) wherein the pressure is maintained at 0.5 Torr (3, 41-43) and molecular hydrogen is flowed at 1 slm for 300 seconds (3, 34-35; 4, 26-30). The bake does not occur at a temperature between 700-900 degrees Celsius. Brabant, however, discloses a hydrogen bake process achieving the same end as Chang, that is, the removal of an oxide film [0102]. The reference states that a suitable temperature condition for the removal of an oxide would range from 750-900 degrees Celsius. Given this disclosure, it would have been obvious to one of ordinary skill in the art at the time the invention was made to execute the hydrogen bake from within the range disclosed by Brabant to achieve the predictable result of removing a native oxide. It would be obvious to execute the hydrogen cleaning steps within the apparatus of Ballantine to achieve the predictable result of removing wafer contaminants prior to deposition.

Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Tsao, Ballantine, Shao, Beinglass, and Chang in view of Adetutu, 5,958,508.

Ballantine is silent regarding the thickness of the deposited metal film. In supplementation, Chang deposits a one-micron tungsten film in the presence of argon (5, 14-17) and at a pressure of 200 milliTorr (5, 20-24). The prior art does not use a sputtering method to deposit the metal; nevertheless, such methods are well-known in the art. For instance, Adetutu, disclosing a method of semiconductor fabrication, states that it would be suitable to deposit a tungsten layer by using either chemical vapor deposition (as does Chang and Ballantine) or sputtering (2, 40-42; 3, 18ff). Given Adetutu's affirmation of the art-recognized equivalence of CVD and sputtering for the purposes of delivering tungsten during semiconductor fabrication, it would have been obvious to one of ordinary skill in the art at the time the invention was made to deposit a metal by using a sputtering method.

Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine and Shao in view of Tsao, Beinglass and in further view of Aoki, US 5,242,666.

Although Beinglass performs the silicide formation at a pressure of only 500 millitorr (4, 40-45), it is well-known in the art that MOSFET formations can occur at the ultra-high vacuum conditions claimed by the applicant. For example, Aoki, disclosing a method of fabricating a MOSFET, maintains a pressure below  $10^{-8}$  torr, thereby demonstrating the art-recognized suitability of such processing conditions (3, 40-50; 4, 26-29). It would have been

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obvious to one of ordinary skill in the art at the time the invention was made to employ these pressure to achieve the predictable result of MOSFET fabrication.

Claim 12 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ballantine and Shao in view of Tsao, Ballantine, Beinglass, and Aoki and in further view of Yamoto et al., US 6,399,429.

Tsao does not address the conditions of formation of the sacrificial oxide film. Aoki, as described above, forms a MOSFET under operating conditions wherein the substrate temperature is maintained between 500-800 degrees Celsius and the pressure is below  $10^{-8}$  torr (3, 45-50). However, the gas type and potential flow rates are not addressed. Supplementing this deficiency is Yamoto, who teaches a method of MOSFET formation. During a step of oxide formation,  $\text{SiH}_4$  is provided at a flow rate of 9 sccm for 166 seconds, thereby demonstrating the suitability of these conditions for MOSFET formation (7, 1ff). Further, both flow rate and deposition time are result effective variables; accordingly, it would have been obvious to one of ordinary skill to execute deposition under the claimed processing conditions since it has been held that discovering the optimum value of a result effective variable involves only routine skill in art (*In re Boesch*, 617 F.2d 272, 205 USPQ 215).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan K. Ford whose telephone number is 571-270-1880. The examiner can normally be reached on M-F, 8:30-5:00 EDT. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Michael Cleveland, can be reached at 571-272-1418. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

/N. K. F./

Examiner, Art Unit 1792

/Karla Moore/

Primary Examiner, Art Unit 1792